

MCUXSDKMIMXRT6XXRN

MCUXpresso SDK Release Notes for EVK-MIMXRT685

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Release notes

Document Information

Information	Content
Keywords	MCUXpresso SDK, Release Notes, EVK-MIMXRT685
Abstract	This document describes the MCUXpresso SDK release notes for EVK-MIMXRT685.



1 Overview

The MCUXpresso SDK is a comprehensive software enablement package designed to simplify and accelerate application development with Arm Cortex-M-based devices from NXP, including its general purpose, crossover and Bluetooth-enabled MCUs. MCUXpresso SW and Tools for DSC further extends the SDK support to current 32-bit Digital Signal Controllers. The MCUXpresso SDK includes production-grade software with integrated RTOS (optional), integrated enabling software technologies (stacks and middleware), reference software, and more.

In addition to working seamlessly with the MCUXpresso IDE, the MCUXpresso SDK also supports and provides example projects for IAR, KEIL, and GCC with Cmake. Support for the MCUXpresso Config Tools allows easy cloning of existing SDK examples and demos, allowing users to leverage the existing software examples provided by the SDK for their own projects.

Underscoring our commitment to high quality, the MCUXpresso SDK is MISRA compliant and checked with Coverity static analysis tools. For details on MCUXpresso SDK, see [MCUXpresso-SDK: Software Development Kit for MCUXpresso](#).

2 MCUXpresso SDK

As part of the MCUXpresso software and tools, MCUXpresso SDK is the evolution of Kinetis SDK, includes support for LPC, DSC, and i.MX System-on-Chip (SoC). The same drivers, APIs, and middleware are still available with support for Kinetis, LPC, DSC, and i.MX silicon. The MCUXpresso SDK adds support for the MCUXpresso IDE, an Eclipse-based toolchain that works with all MCUXpresso SDKs. Easily import your SDK into the new toolchain to access to all of the available components, examples, and demos for your target silicon. In addition to the MCUXpresso IDE, support for the MCUXpresso Config Tools allows easy cloning of existing SDK examples and demos, allowing users to leverage the existing software examples provided by the SDK for their own projects.

In order to maintain compatibility with legacy Freescale code, the filenames and source code in MCUXpresso SDK containing the legacy Freescale prefix FSL has been left as is. The FSL prefix has been redefined as the NXP Foundation Software Library.

3 Development tools

The MCUXpresso SDK is compiled and tested with these development tools:

- Keil MDK, version is 5.38.a
- MCUXpresso IDE, version is 11.8.0
- GCC Arm Embedded, version is 12.2.Rel1
- IAR Embedded Workbench for Arm, version is 9.40
- Xtensa C Compiler, version is RI-2021.8-win32
- Xtensa Xplorer, version is 9.0.18

4 Supported development system

This release supports boards and devices listed in table below. The boards and devices in bold were tested in this release.

Table 1. Supported boards and devices

Development boards	MCU devices
EVK-MIMXRT685	MIMXRT685SFVKB , MIMXRT633SFAWBR, MIMXRT685SFFOB, MIMXRT633SFFOB, MIMXRT685SFAWBR, MIMXRT685SFVKB, MIMXRT633SFVKB

5 MCUXpresso SDK release package

The MCUXpresso SDK release package content is aligned with the silicon subfamily it supports. This includes the boards, devices, documentation, and middleware.

5.1 Device support

The device folder contains the whole software enablement available for the specific System-on-Chip (SoC) subfamily. This folder includes clock-specific implementation, device register header files, device register feature header files, and the system configuration source files. Included with the standard SoC support are folders containing peripheral drivers, toolchain support, and a standard debug console. The device-specific header files provide a direct access to the microcontroller peripheral registers. The device header file provides an overall SoC memory mapped register definition. The folder also includes the feature header file for each peripheral on the microcontroller. The toolchain folder contains the startup code and linker files for each supported toolchain. The startup code efficiently transfers the code execution to the main() function.

5.1.1 Board support

The boards folder provides the board-specific demo applications, driver examples, and middleware examples.

5.1.2 Demo application and other examples

The demo applications demonstrate the usage of the peripheral drivers to achieve a system level solution. Each demo application contains a readme file that describes the operation of the demo and required setup steps. The driver examples demonstrate the capabilities of the peripheral drivers. Each example implements a common use case to help demonstrate the driver functionality.

5.2 CMSIS DSP Library

The MCUXpresso SDK is shipped with the standard CMSIS development pack, including the prebuilt libraries.

5.3 Operating System

5.3.1 FreeRTOS

Real-time operating system for microcontrollers from Amazon.

5.4 Middleware

5.4.1 AWS IoT

Amazon Web Service (AWS) IoT Core SDK.

5.4.2 DSP Audio Streamer

DSP Audio Streamer Framework based on Xtensa Audio Framework from Cadence Design Systems for Xtensa DSP Audio Engines.

5.4.3 DSP Neural Networks

DSP Neural Networks Framework based on Xtensa Neural Networks Library from Cadence Design Systems for Xtensa HiFi Audio Engines.

5.4.4 Essential Audio Processing Library

Audio processing blocks for enhancing the tonal and spatial perception of sound in audio applications.

5.4.5 eIQ

eIQ machine learning SDK containing:

- Arm CMSIS-NN library (neural network kernels optimized for Cortex-M cores)
- Inference engines:
 - TensorFlow Lite Micro
 - DeepView RT
- Example code for TensorFlow Lite Micro, Glow, and DeepView RT

5.4.6 emWin

The MCUXpresso SDK is pre-integrated with the SEGGER emWin GUI middleware. The AppWizard provides developers and designers with a flexible tool to create stunning user interface applications, without writing any code.

5.4.7 Fatfs

The FatFs file system is integrated with the MCUXpresso SDK and can be used to access either the SD card or the USB memory stick when the SD card driver or the USB Mass Storage Device class implementation is used.

5.4.8 FreeMASTER

FreeMASTER communication driver for 32-bit platforms.

5.4.9 IoT Sensing Software Development Kit (ISSDK)

The IoT Sensing Software Development Kit (ISSDK) is the embedded software framework enabling the NXP digital and analog sensors for IoT applications. ISSDK combines a set of robust sensor drivers and algorithms along with example applications that allow users to get started with using NXP IoT motion & pressure sensors. ISSDK is being offered as a middleware component in MCUXpresso SDK.

5.4.10 LVGL

LVGL Open Source Graphics Library

5.4.11 lwIP

The lwIP TCP/IP stack is pre-integrated with MCUXpresso SDK and runs on top of the MCUXpresso SDK Ethernet driver with Ethernet-capable devices/boards.

For details, see the *lwIP TCP/IP Stack and MCUXpresso SDK Integration User's Guide* (document MCUXSDKLWIPUG).

5.4.12 Maestro Audio Framework for MCU

Maestro Audio Framework library for MCU

5.4.13 Mbed Crypto

Mbed Crypto library

5.4.14 Motor Control Software (ACIM, BLDC, PMSM)

Motor control examples.

5.4.15 mbedTLS

mbedtls SSL/TLS library

5.4.16 MCU Boot

MCU Bootloader source code.

5.4.17 multicore

Multicore Software Development Kit

5.4.18 NatureDSP

Digital Signal Processing for Xtensa DSP Audio Engines.

5.4.19 Nghttp2 HTTP/2 C Library

C library implementation of HTTP/2

5.4.20 NXP Wi-Fi

The MCUXpresso SDK provides driver for NXP Wi-Fi external modules. The Wi-Fi driver is integrated with LWIP TCP/IP stack and demonstrated with several network applications (iperf and AWS IoT).

For more information, see *Getting Started with NXP based Wireless Modules and i.MX RT Platform Running on RTOS* (document: UM11441).

5.4.21 PSA Test Suite

Arm Platform Security Architecture Test Suite

5.4.22 sdmmc stack

The SDMMC software is integrated with MCUXpresso SDK to support SD/MMC/SDIO standard specification. This also includes a host adapter layer for bare-metal/RTOS applications.

5.4.23 TF-M

Trusted Firmware - M Library

5.4.24 USB Host, Device, OTG Stack

See the MCUXpresso SDK USB Stack User's Guide (document MCUXSDKUSBSUG) for more information.

5.4.25 USB Type-C Power Delivery Authentication

USB Type-C Power Delivery Authentication

5.4.26 USB Type-C PD Stack

See the *MCUXpresso SDK USB Type-C PD Stack User's Guide* (document MCUXSDKUSBPDUG) for more information.

Note: The USB TYPE-C PD stack supports IAR only.

5.4.27 Voice intelligent technology library

Voice Intelligent Technology (VIT) Library.

5.4.28 Wireless EdgeFast Bluetooth PAL

For more information, see the MCUXpresso SDK EdgeFast Bluetooth Protocol Abstraction Layer User's Guide.

6 Release contents

[Table 2](#) provides an overview of the MCUXpresso SDK release package contents and locations.

Table 2. MCUXpresso SDK release package contents and locations

Deliverable	Location
Boards	INSTALL_DIR/boards
Demo Applications	INSTALL_DIR/boards/<board_name>/demo_apps
Driver Examples	INSTALL_DIR/boards/<board_name>/driver_examples
Board Project Template for MCUXpresso IDE NPW	INSTALL_DIR/boards/<board_name>/project_template
Driver, SoC header files, extension header files and feature header files, utilities	INSTALL_DIR/devices/<device_name>
Peripheral drivers	INSTALL_DIR/devices/<device_name>/drivers
Toolchain linker files and startup code	INSTALL_DIR/devices/<device_name>/<toolchain_name>
Utilities such as debug console	INSTALL_DIR/devices/<device_name>/utilities
Device Project Template for MCUXpresso IDE NPW	INSTALL_DIR/devices/<device_name>/project_template
CMSIS Arm Cortex-M header files, DSP library source	INSTALL_DIR/CMSIS

Table 2. MCUXpresso SDK release package contents and locations...continued

Deliverable	Location
Components and board device drivers	INSTALL_DIR/components
RTOS	INSTALL_DIR/rtos
Release Notes, Getting Started Document and other documents	INSTALL_DIR/docs
Tools such as shared cmake files	INSTALL_DIR/tools
Middleware	INSTALL_DIR/middleware

7 MISRA compliance

All MCUXpresso SDK drivers comply to MISRA 2012 rules with exceptions in [Table 3](#).

Table 3. MISRA exception rules

Exception rules	Description
Directive 4.4	Sections of code should not be commented out.
Directive 4.5	Identifiers in the same name space with overlapping visibility should be typographically unambiguous.
Directive 4.6	Typedefs that indicate size and signedness should be used in place of the basic numerical types.
Directive 4.8	If a pointer to a structure or union is never dereferenced within a translation unit, then the implementation of the object should be hidden.
Directive 4.9	A function should be used in preference to a function-like macro where they are interchangeable.
Directive 4.13	Functions which are designed to provide operations on a resource should be called in an appropriate sequence.
Rule 1.2	Language extensions should not be used.
Rule 2.3	A project should not contain unused type declarations.
Rule 2.4	A project should not contain unused tag declarations.
Rule 2.5	A project should not contain unused macro declarations.
Rule 2.6	A function should not contain unused label declarations.
Rule 2.7	There should be no unused parameters in functions.
Rule 4.2	Trigraphs should not be used.
Rule 5.1	External identifiers shall be distinct.
Rule 5.4	Macro identifiers shall be distinct.
Rule 5.9	Identifiers that define objects or functions with internal linkage should be unique.
Rule 8.7	Functions and objects should not be defined with external linkage if they are referenced in only one translation unit.
Rule 8.9	An object should be defined at block scope if its identifier only appears in a single function.
Rule 8.11	When an array with external linkage is declared, its size should be explicitly specified.

Table 3. MISRA exception rules...continued

Exception rules	Description
Rule 8.13	A pointer should point to a const-qualified type whenever possible.
Rule 10.5	The value of an expression should not be cast to an inappropriate essential type.
Rule 11.4	A conversion should not be performed between a pointer to object and an integer type.
Rule 11.5	A conversion should not be performed from pointer to void into pointer to object.
Rule 12.1	The precedence of operators within expressions should be made explicit.
Rule 12.3	The comma operator should not be used.
Rule 12.4	Evaluation of constant expressions should not lead to unsigned integer wrap-around.
Rule 13.3	A full expression containing an increment (++) or decrement (--) operator should have no other potential side effects other than that caused by the increment or decrement operator.
Rule 15.4	There should be no more than one break or go to statement used to terminate any iteration statement.
Rule 17.5	The function argument corresponding to a parameter declared to have an array type shall have an appropriate number of elements.
Rule 17.8	A function parameter should not be modified.
Rule 19.2	The union keyword should not be used.
Rule 20.1	#include directives should only be preceded by preprocessor directives or comments.
Rule 20.10	The # and ## preprocessor operators should not be used.
Rule 21.1	#define and #undef shall not be used on a reserved identifier or reserved macro name.
Rule 21.2	A reserved identifier or macro name shall not be declared.
Rule 21.12	The exception handling features of <fenv.h> should not be used.

8 Known Issues

This section lists the known issues, limitations, and/or workarounds.

8.1 Maximum file path length in Windows 7 operating system

The Windows 7 operating system imposes a 260-character maximum length for file paths. When installing the MCUXpresso SDK, place it in a directory close to the root to prevent file paths from exceeding the maximum character length specified by the Windows operating system. The recommended location is the C:\<folder>.

8.2 New Project Wizard compile failure

The following components request the user to manually select other components that they depend upon in order to compile.

These components depend on several other components and the New Project Wizard (NPW) is not able to decide which one is needed by the user.

Note: *xxx means core variants, such as, cm0plus, cm33, cm4, cm33_nodsp.*

Components:issdk_mag3110, issdk_host, systick, gpio_kinetis, gpio_lpc, issdk_mpl3115, sensor_fusion_agm01, sensor_fusion_agm01_lpc, issdk_mma845x, issdk_mma8491q, issdk_mma865x, issdk_mma9553,

Also for low-level adapter components, currently the different types of the same adapter cannot be selected at the same time.

For example, if there are two types of timer adapters, gpt_adapter and pit_adapter, only one can be selected as timer adapter

in one project at a time. Duplicate implementation of the function results in an error.

Note: *Most of middleware components have complex dependencies and are not fully supported in new project wizard. Adding a middleware component may result in compile failure.*

8.3 Low speed devices not supported

The host examples cannot support low-speed devices

8.4 IAR cannot debug RAM application with J-Link

Currently, IAR will call J-Link reset after the application is downloaded to SRAM, but such operation will cause SRAM data lost.

Here is a workaround to avoid real reset, with the cost of no any reset during the debugging, and hardware status uncleared.

1. Build and debug IAR project once and see the settings folder created.
2. Create the `_.JLinkScript` file in the settings folder with the following contents.

```
void ResetTarget(void) {  
    JLINK_TARGET_Halt();  
}
```

3. Debug the project again and now it can work.

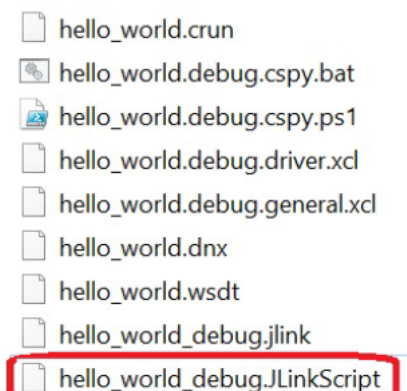


Figure 1. hello_world JLink script example

8.5 CMSIS PACK new project compile failure

The generated configuration cannot be applied globally. The components, serial_manager_usb_cdc_virtual and serial_manager_usb_cdc_virtual_xxx (xxx means core variants like cm0plus, cm33, cm4, and cm33_nodsp) are unsupported for new project wizard of CMSIS pack and will lead to compile failure if selected while creating new project(s).

8.6 Dsp_xaf_demo cannot handle certain audio file types

Audio files encoded using ffmpeg tool and Lavf/Lavc codec cannot be played. M4A format of AAC files is not supported either.

If the demo stops responding while trying to play any of unsupported files, reset the board.

8.7 Cannot add SDK components into FreeRTOS projects

It is not possible to add any SDK components into FreeRTOS project using the MCUXpresso IDE New Project wizard.

8.8 lwip_httpsrv_ota_wifi example fails to accept the new image on EVKMIMXRT685

After uploading the new image over https, and rebooting the board the new image starts. However, reboot starts it is not possible to accept the update and make it permanent. This issue is specific to combination of EVKMIMXRT685 board and AW-NM191NF-uSD Wi-Fi module. Other configurations are not affected.

8.9 Board may reset itself when running SD card related cases

Board may reset itself when running SD card related cases. However, the issue is not reproduced if more power supply is connected.

8.10 Log output may be mixed in shell/hfp example

When multiple tasks print the log, the serial port terminal output has the probability to appear mixed.

8.11 LE encryption failure causes connection to fail

There can be a corner case when LE link encryption can fail. This occurs when device under test (DUT); RT Bluetooth controller here, while waiting for the response to LL_SLAVE_FEATURES_REQ, instead receives the LL_ENC_REQ response from a remote device.

This causes deadlock scenario where DUT and remote devices are stuck waiting for response from peer.

8.12 Connection disconnects with 7.5 ms connection interval

When wireless example works as a peripheral, the central role with 7.5 ms connection interval connects to the wireless example. However, when using the 6th/7th/8th central to connect the wireless example, all the previous connections with the previous centrals are disconnected.

When wireless example works as central and the connection interval is 7.5 ms, the 4th peripheral is not scanned.

8.13 a2dp sink demo: Noise may occur when phone plays music with other operations

Noise may occur when phone plays music with other operations.

For example:

- Switches the WIFI network of the phone when playing music
- Switches music when playing the online music

8.14 Volume is very loud from codec in the a2dp sink and hfp demos

After connecting to the phone and playing music or calling, the codec volume is very loud.

8.15 Wireless EdgeFast_Bluetooth stack is not supported by any kits

Wireless EdgeFast_Bluetooth stack can be downloaded by EVK-MIMXRT685-AGM01 and EVK-MIMXRT685-OM13790HOST in <https://mcuxpresso.nxp.com/en/welcome>. However, it is not supported in these kits.

9 Change Log

Change log of software components included in the package, see MCUXpresso SDK ChangeLog_MIMXRT685S.pdf.

10 Legal information

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Contents

1	Overview	2		
2	MCUXpresso SDK	2		
3	Development tools	2		
4	Supported development system	2		
5	MCUXpresso SDK release package	3		
5.1	Device support	3	8.6	Dsp_xaf_demo cannot handle certain audio file types
5.1.1	Board support	3	8.7	Cannot add SDK components into FreeRTOS projects
5.1.2	Demo application and other examples	3	8.8	lwip_httpsrv_ota_wifi example fails to accept the new image on EVKMIMXRT685
5.2	CMSIS DSP Library	3	8.9	Board may reset itself when running SD card related cases
5.3	Operating System	3	8.10	Log output may be mixed in shell/hfp example
5.3.1	FreeRTOS	3	8.11	LE encryption failure causes connection to fail
5.4	Middleware	3	8.12	Connection disconnects with 7.5 ms connection interval
5.4.1	AWS IoT	3	8.13	a2dp sink demo: Noise may occur when phone plays music with other operations
5.4.2	DSP Audio Streamer	4	8.14	Volume is very loud from codec in the a2dp sink and hfp demos
5.4.3	DSP Neural Networks	4	8.15	Wireless EdgeFast Bluetooth stack is not supported by any kits
5.4.4	Essential Audio Processing Library	4	9	Change Log
5.4.5	elQ	4	10	Legal information
5.4.6	emWin	4		
5.4.7	Fatfs	4		
5.4.8	FreeMASTER	4		
5.4.9	IoT Sensing Software Development Kit (ISSDK)	4		
5.4.10	LVGL	4		
5.4.11	lwIP	5		
5.4.12	Maestro Audio Framework for MCU	5		
5.4.13	Mbed Crypto	5		
5.4.14	Motor Control Software (ACIM, BLDC, PMSM)	5		
5.4.15	mbedTLS	5		
5.4.16	MCU Boot	5		
5.4.17	multicore	5		
5.4.18	NatureDSP	5		
5.4.19	Nghhttp2 HTTP/2 C Library	5		
5.4.20	NXP Wi-Fi	5		
5.4.21	PSA Test Suite	5		
5.4.22	sdmmc stack	6		
5.4.23	TF-M	6		
5.4.24	USB Host, Device, OTG Stack	6		
5.4.25	USB Type-C Power Delivery Authentication	6		
5.4.26	USB Type-C PD Stack	6		
5.4.27	Voice intelligent technology library	6		
5.4.28	Wireless EdgeFast Bluetooth PAL	6		
6	Release contents	6		
7	MISRA compliance	7		
8	Known Issues	8		
8.1	Maximum file path length in Windows 7 operating system	8		
8.2	New Project Wizard compile failure	9		
8.3	Low speed devices not supported	9		
8.4	IAR cannot debug RAM application with J-Link	9		
8.5	CMSIS PACK new project compile failure	10		

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